

# Kuo-Hsiang Chien

## List of Publications by Year in descending order

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14  
papers

511  
citations

840776

11  
h-index

1058476

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docs citations

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times ranked

280  
citing authors

#	ARTICLE	IF	CITATIONS
1	Multicolor Emission from Ultraviolet GaN-Based Photonic Quasicrystal Nanopyramid Structure with Semipolar InxGa1-xN/GaN Multiple Quantum Wells. <i>Nanoscale Research Letters</i> , 2021, 16, 145.	5.7	1
2	Heat transfer of vapor chamber with different types of microchannels. <i>International Journal of Green Energy</i> , 2016, 13, 1325-1333.	3.8	6
3	A novel double pipe pulsating heat pipe design to tackle inverted heat source arrangement. <i>Applied Thermal Engineering</i> , 2016, 106, 697-701.	6.0	25
4	An Experimental Investigation of Micro Pulsating Heat Pipes. <i>Micromachines</i> , 2014, 5, 385-395.	2.9	22
5	Investigation of the performance of pulsating heat pipe subject to uniform/alternating tube diameters. <i>Experimental Thermal and Fluid Science</i> , 2014, 54, 85-92.	2.7	79
6	Heat Transfer Characteristics in High Power LED Packaging. <i>Smart Science</i> , 2014, 2, 1-6.	3.2	10
7	A novel design of pulsating heat pipe with fewer turns applicable to all orientations. <i>International Journal of Heat and Mass Transfer</i> , 2012, 55, 5722-5728.	4.8	130
8	Theoretical study of oscillatory phenomena in a horizontal closed-loop pulsating heat pipe with asymmetrical arrayed minichannel. <i>International Communications in Heat and Mass Transfer</i> , 2012, 39, 923-930.	5.6	16
9	On the Heat Transfer Characteristics of Heat Sinks: With and Without Vortex Generators. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2010, 33, 391-397.	1.3	27
10	An experimental investigation of air cooling thermal module using various enhancements at low Reynolds number region. <i>International Journal of Heat and Mass Transfer</i> , 2010, 53, 5675-5681.	4.8	42
11	Numerical simulation of a heat sink embedded with a vapor chamber and calculation of effective thermal conductivity of a vapor chamber. <i>Applied Thermal Engineering</i> , 2009, 29, 2655-2664.	6.0	63
12	Investigations of the Thermal Spreading Effects of Rectangular Conduction Plates and Vapor Chamber. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2007, 129, 348-355.	1.8	30
13	On the heat transfer characteristics of heat sinks: Influence of fin spacing at low Reynolds number region. <i>International Journal of Heat and Mass Transfer</i> , 2007, 50, 2667-2674.	4.8	30
14	A simplified transient three-dimensional model for estimating the thermal performance of the vapor chambers. <i>Applied Thermal Engineering</i> , 2006, 26, 2087-2094.	6.0	30